

## P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>c</sup>	Q <sub>g</sub> (Typ.)
- 20	0.34 at V <sub>GS</sub> = - 4.5 V	- 0.75	1.3 nC
	0.49 at V <sub>GS</sub> = - 2.5 V	- 0.53	

### FEATURES

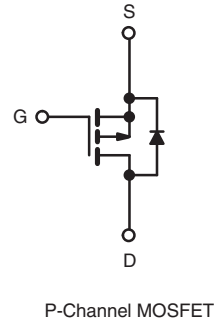
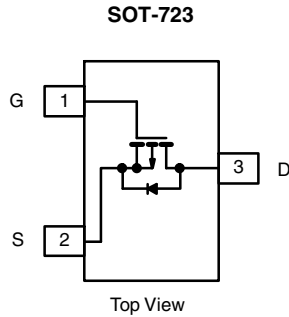
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Load Switch
- DC/DC Converters



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	- 20	V
Gate-Source Voltage		V <sub>GS</sub>	± 12	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	- 0.75	A
	T <sub>C</sub> = 70 °C		- 0.5	
	T <sub>A</sub> = 25 °C		- 0.7 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		- 0.5 <sup>a, b</sup>	
Pulsed Drain Current		I <sub>DM</sub>	- 3	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	- 0.4	
	T <sub>A</sub> = 25 °C		- 0.3	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	0.25	W
	T <sub>C</sub> = 70 °C		0.2	
	T <sub>A</sub> = 25 °C		0.2 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		0.2 <sup>a, b</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 50 to 150	°C
Soldering Recommendations (Peak Temperature)			260	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Based on T<sub>C</sub> = 25 °C.

**THERMAL RESISTANCE RATINGS**

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a, b</sup>	$t \leq 10$ s	$R_{thJA}$	250	500	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	225	670	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.  
 b. Maximum under steady state conditions is 360 °C/W.

**SPECIFICATIONS** ( $T_J = 25$  °C, unless otherwise noted)

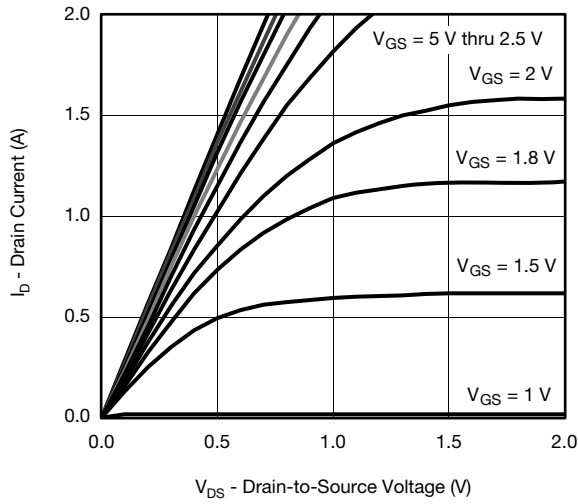
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0$ V, $I_D = -250$ $\mu$ A	- 20			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250$ $\mu$ A		- 14		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			2.4		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250$ $\mu$ A	- 0.45		- 0.8	V
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0$ V, $V_{GS} = \pm 8$ V			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -20$ V, $V_{GS} = 0$ V			- 1	$\mu$ A
		$V_{DS} = -20$ V, $V_{GS} = 0$ V, $T_J = 55$ °C			- 10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \leq -5$ V, $V_{GS} = -4.5$ V	- 2			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = -4.5$ V, $I_D = -0.4$ A		0.34		$\Omega$
		$V_{GS} = -2.5$ V, $I_D = -0.2$ A		0.49		
		$V_{GS} = -1.8$ V, $I_D = -0.3$ A		0.52		
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -5$ V, $I_D = -0.4$ A		5		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -10$ V, $V_{GS} = 0$ V, $f = 1$ MHz		72		pF
Output Capacitance	$C_{oss}$			15		
Reverse Transfer Capacitance	$C_{rss}$			14		
Total Gate Charge	$Q_g$	$V_{DS} = -10$ V, $V_{GS} = -4.5$ V, $I_D = -0.4$ A		1.3	2.5	nC
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -10$ V, $V_{GS} = -2.5$ V, $I_D = -0.4$ A		1.7	2.1	
Gate-Drain Charge	$Q_{gd}$			0.7		
Gate Resistance	$R_g$	$f = 1$ MHz	1.4	7	14	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10$ V, $R_L = 9.1$ $\Omega$ $I_D \cong -0.4$ A, $V_{GEN} = -4.5$ V, $R_g = 1$ $\Omega$		12	20	ns
Rise Time	$t_r$			20	30	
Turn-Off Delay Time	$t_{d(off)}$			23	35	
Fall Time	$t_f$			9	18	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10$ V, $R_L = 9.1$ $\Omega$ $I_D \cong -0.4$ A, $V_{GEN} = -8$ V, $R_g = 1$ $\Omega$		5	10	
Rise Time	$t_r$			10	20	
Turn-Off Delay Time	$t_{d(off)}$			18	27	
Fall Time	$t_f$			7	14	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25$ °C			- 0.7	A
Pulse Diode Forward Current <sup>a</sup>	$I_{SM}$				- 6	
Body Diode Voltage	$V_{SD}$	$I_F = -0.7$ A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = -0.7$ A, $di/dt = 100$ A/ $\mu$ s, $T_J = 25$ °C		18	27	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			7	14	nC
Reverse Recovery Fall Time	$t_a$			7		ns
Reverse Recovery Rise Time	$t_b$			11		

Notes:

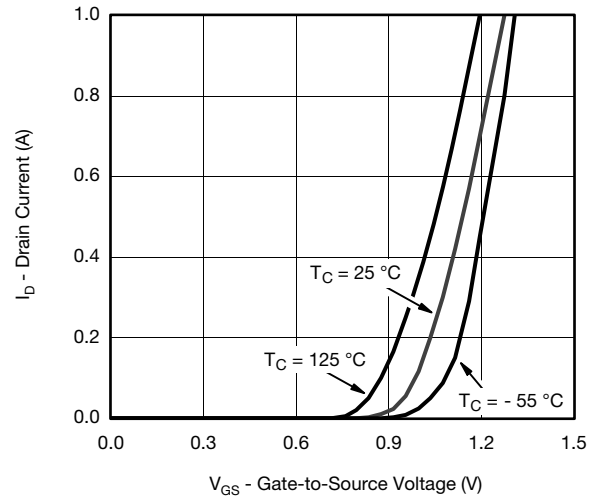
- a. Pulse test; pulse width  $\leq 300$   $\mu$ s, duty cycle  $\leq 2$  %.  
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

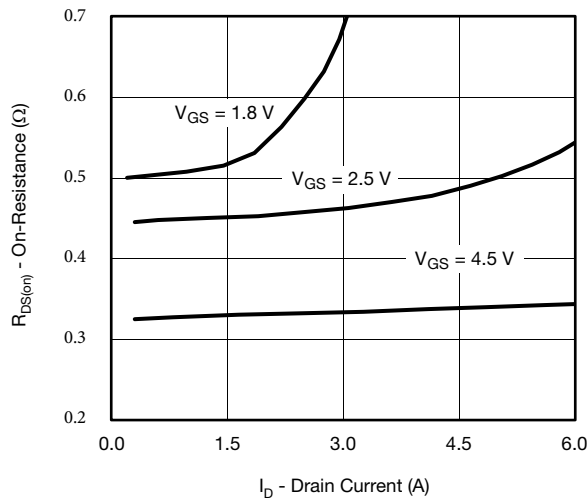
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



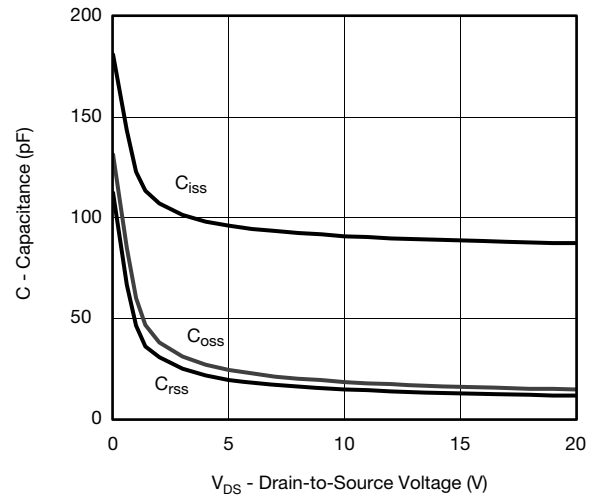
$V_{DS}$  - Drain-to-Source Voltage (V)  
**Output Characteristics**



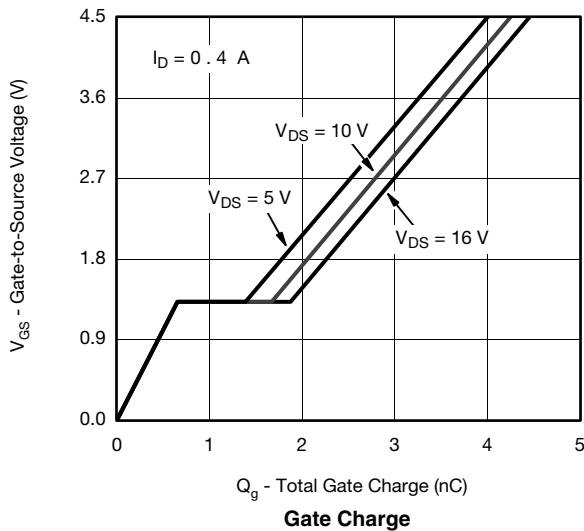
$V_{GS}$  - Gate-to-Source Voltage (V)  
**Transfer Characteristics**



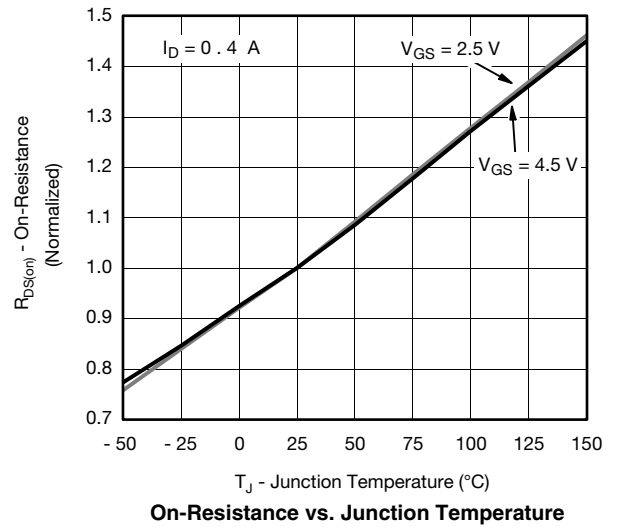
$I_D$  - Drain Current (A)  
**On-Resistance vs. Drain Current**



$V_{DS}$  - Drain-to-Source Voltage (V)  
**Capacitance**

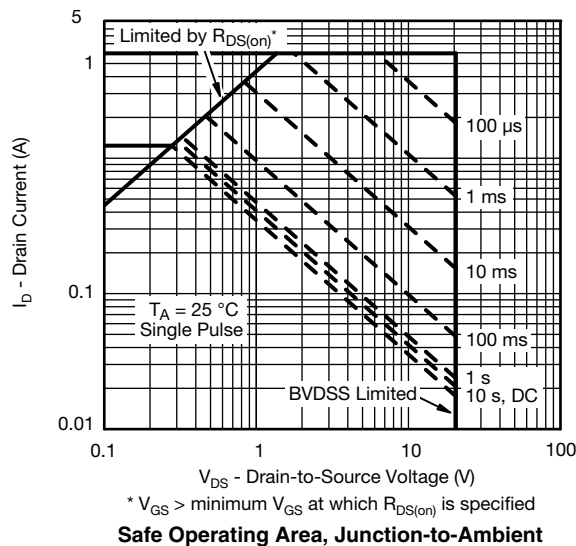
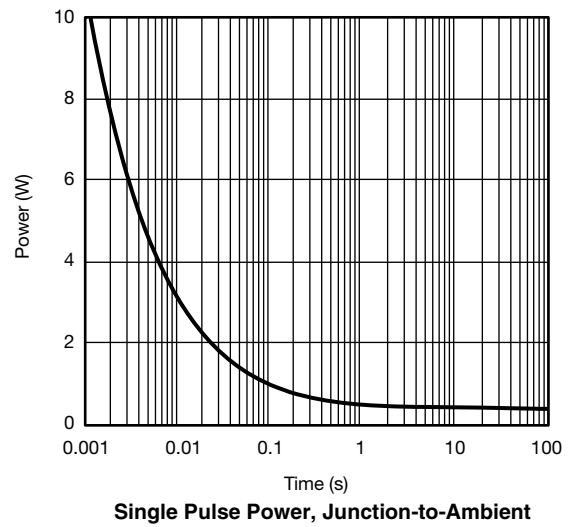
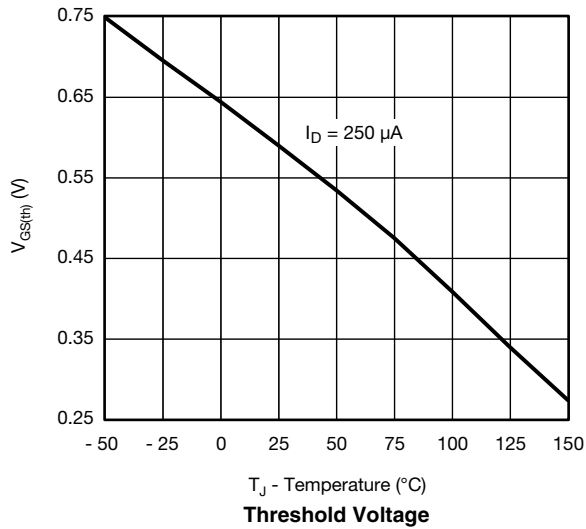
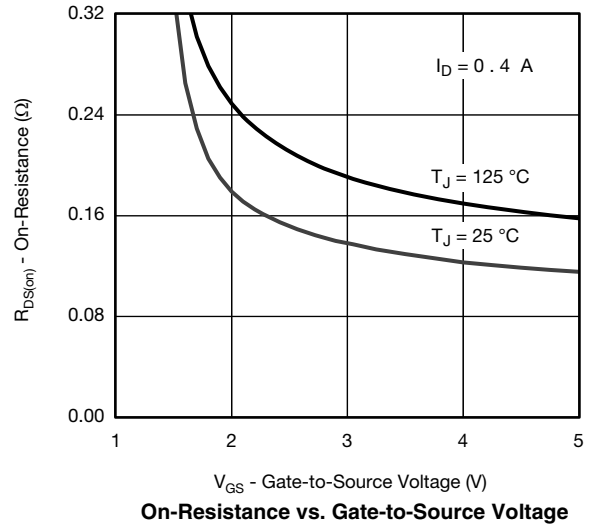
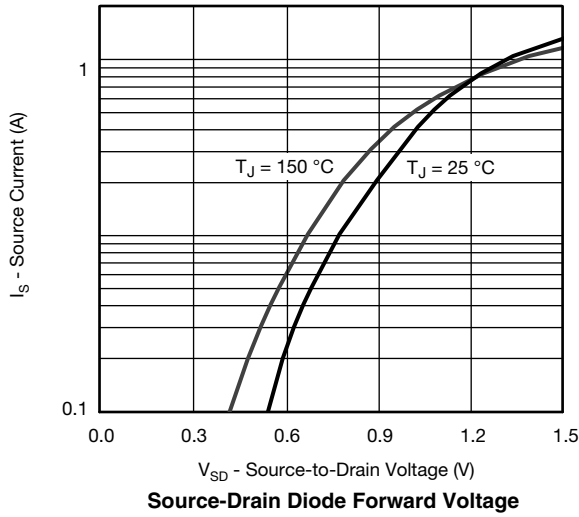


$Q_g$  - Total Gate Charge (nC)  
**Gate Charge**

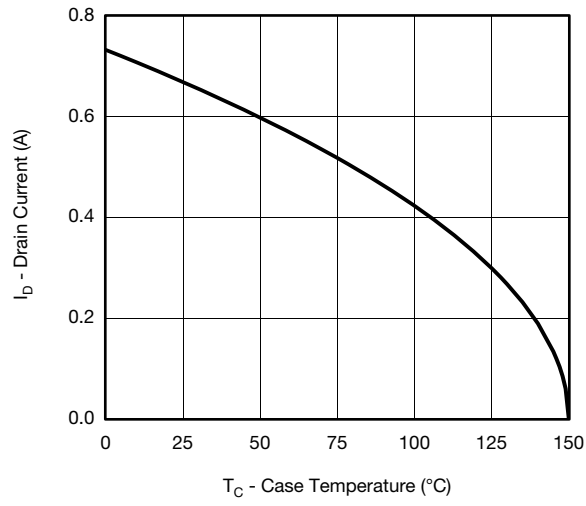


$T_J$  - Junction Temperature (°C)  
**On-Resistance vs. Junction Temperature**

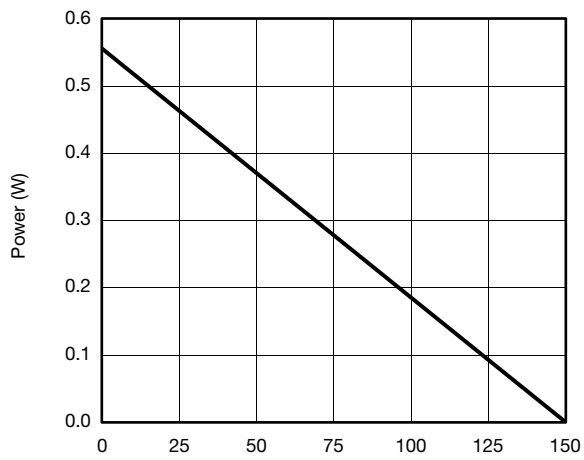
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



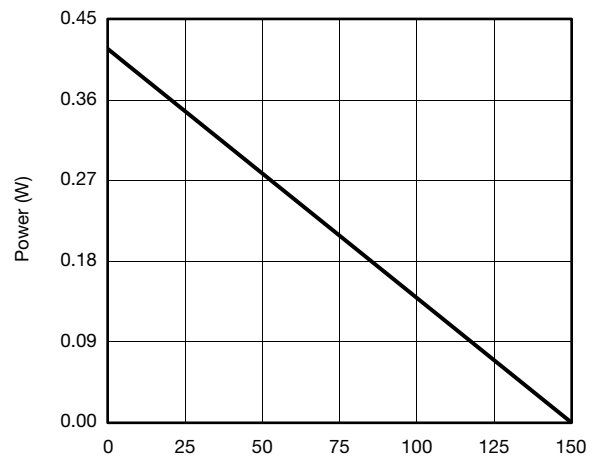
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Current Derating\***



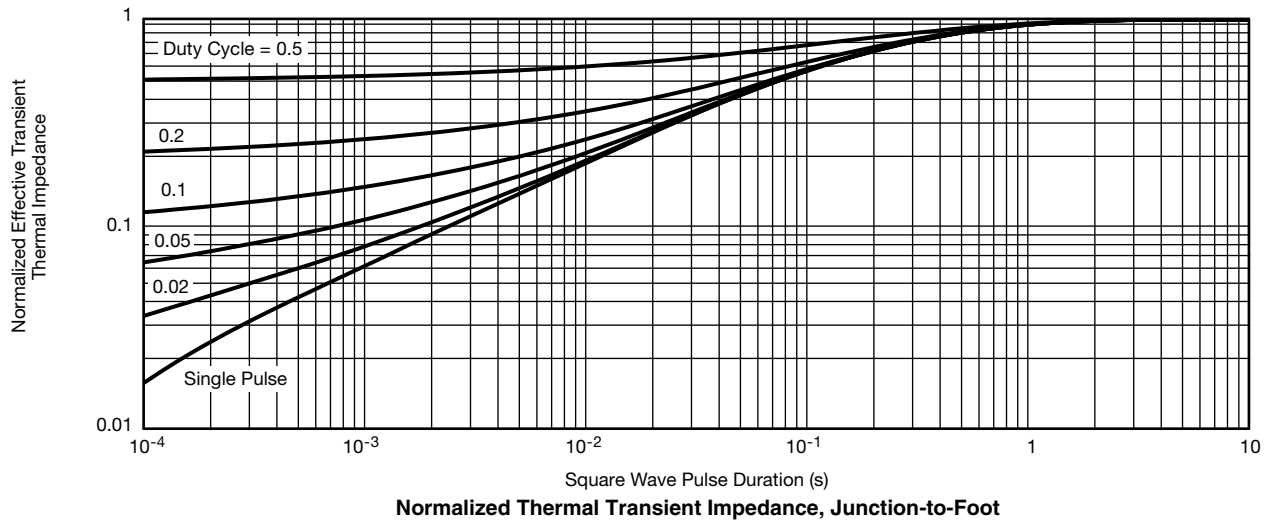
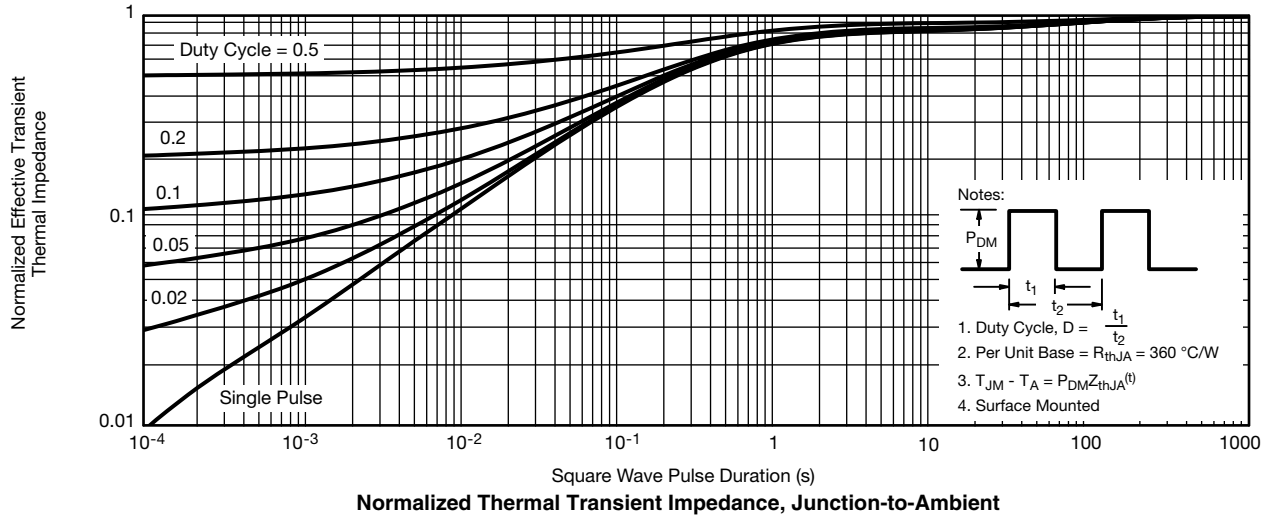
**Power, Junction-to-Case**



**Power, Junction-to-Ambient**

\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

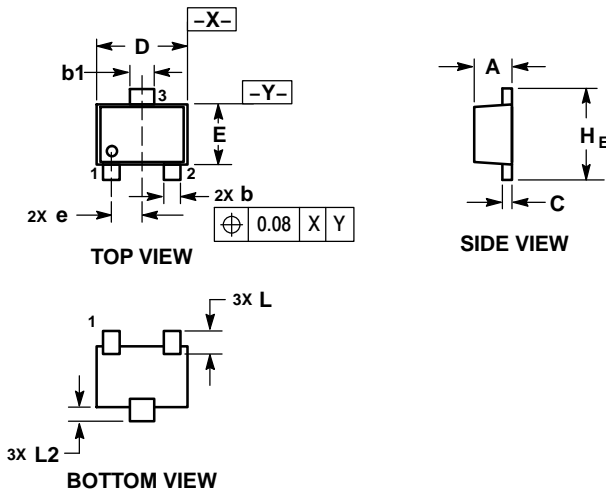
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**SOT-723**



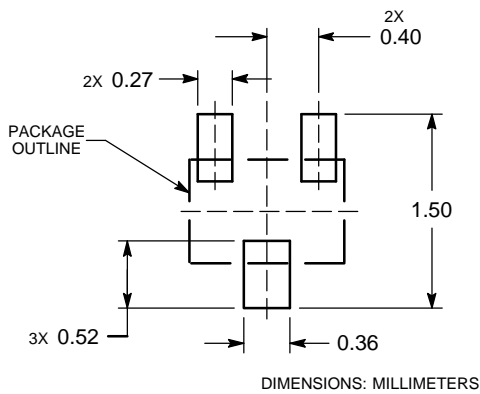
SCALE 4:1



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.45	0.50	0.55
b	0.15	0.21	0.27
b1	0.25	0.31	0.37
C	0.07	0.12	0.17
D	1.15	1.20	1.25
E	0.75	0.80	0.85
e	0.40 BSC		
H <sub>E</sub>	1.15	1.20	1.25
L	0.29 REF		
L2	0.15	0.20	0.25

**RECOMMENDED  
SOLDERING FOOTPRINT\***



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